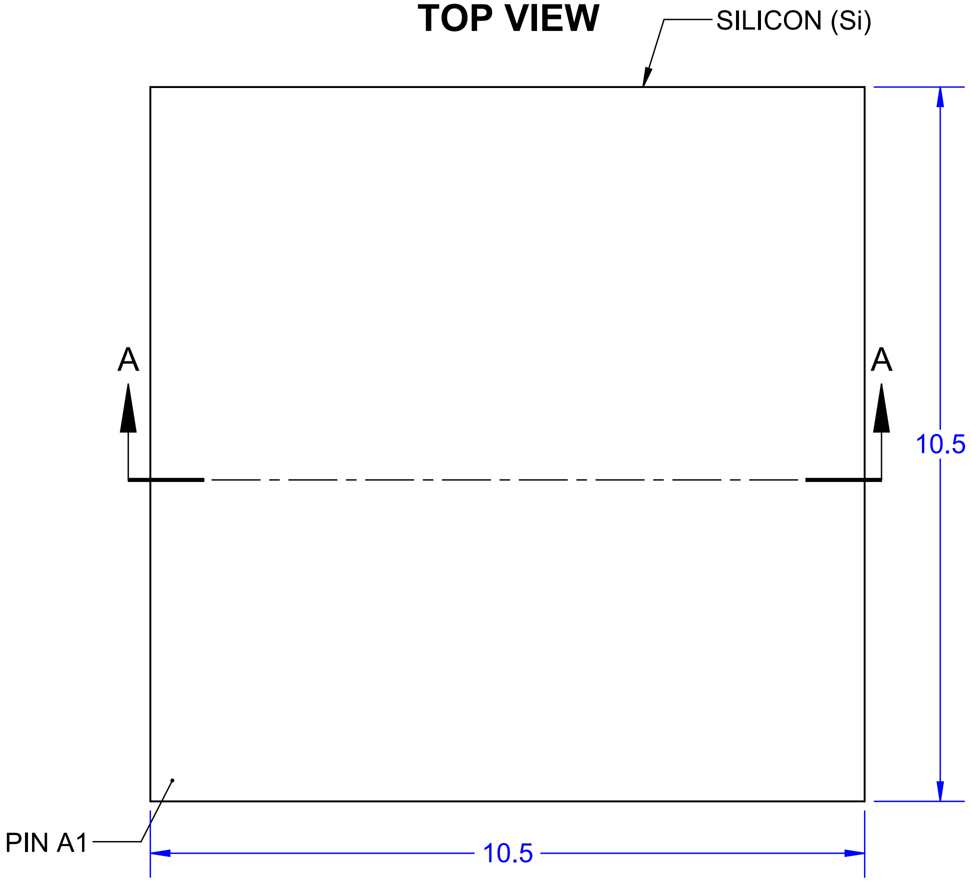
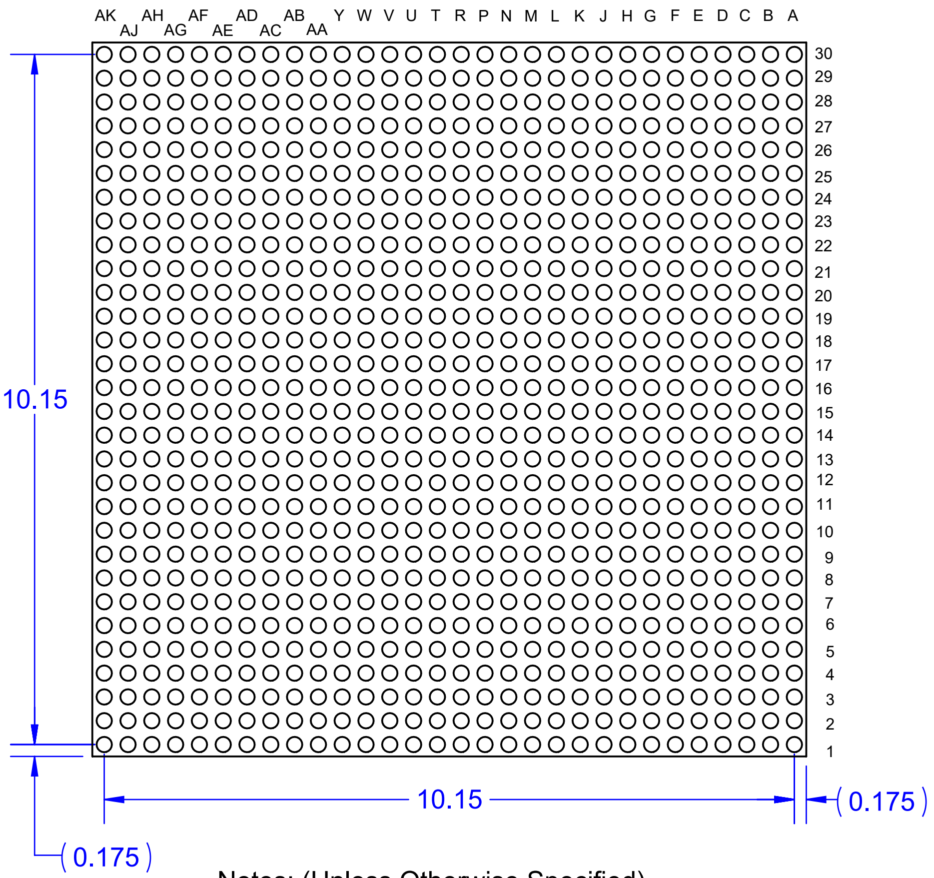
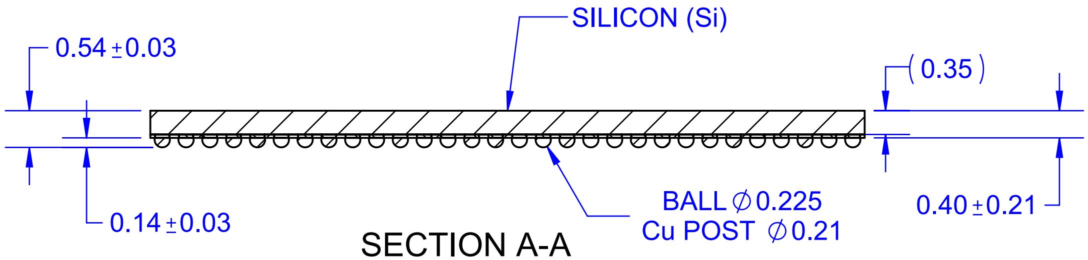
TOP VIEW



BALL VIEW





SECTION A-A
SCALE 9 : 1

Notes: (Unless Otherwise Specified).

1) DIMENSIONS: mm
2) SOLDER BALL ALLOY: SAC305 (Sn96.5/Ag3.0/Cu0.5).
3) BALL DIAMETER (BEFORE REFLOW) ∅0.225mm ±0.03.
4) NON-SOLDER MASK DEFINED PAD.
5) PAD Cu DIAMETER: ∅ 0.21mm.
6) SUBSTRATE MATERIAL: Si (SILICON).
7) DAISY CHAIN PATTERN (SEE PAGE 2).

PART NUMBER TABLE

PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
WLP900T.35C-DC307D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES

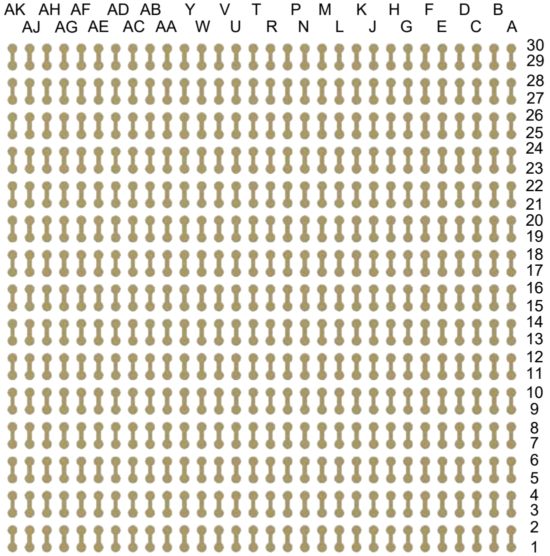
APPROVALS		DATE
DRAWN	T.Au	7/1/2023
ENG	M. Hart	7/1/2023
MFG		
QA		
CUST		
REVISED		

TopLine®

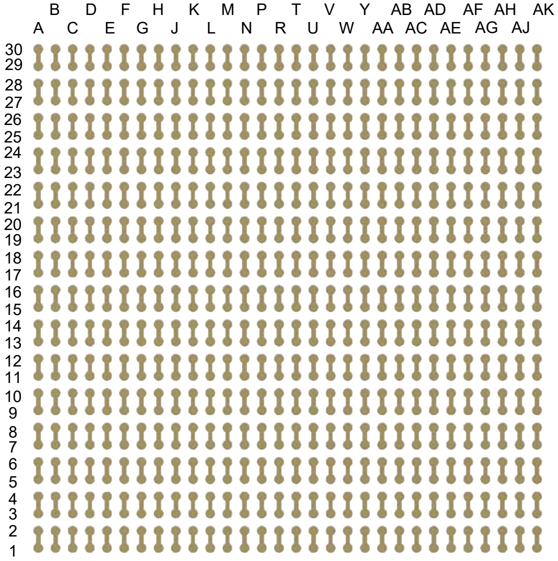
TITLE	WLP900T.35C-DC307D 900 BALL P=0.35mm		
SCALE 40:1	SIZE A	DRAWING NO. 573070	REV A
DO NOT SCALE DRAWING			SHEET 1 OF 5

DAISY CHAIN PATTERN

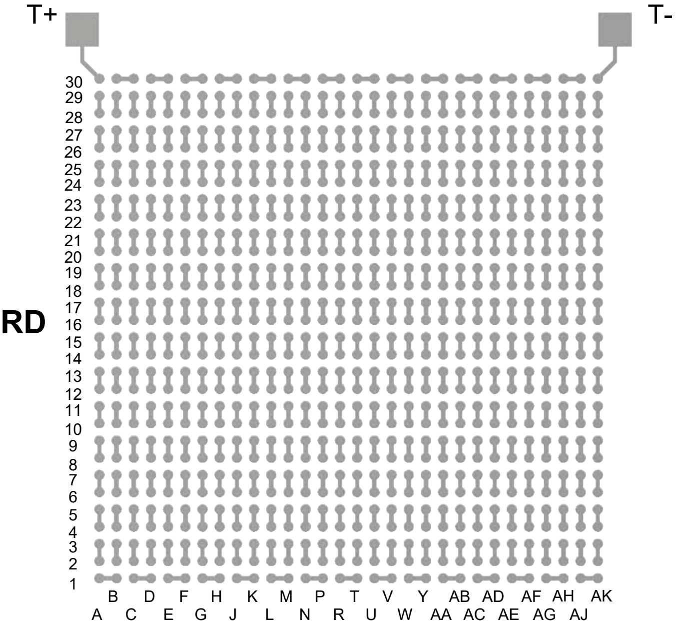
BALL VIEW



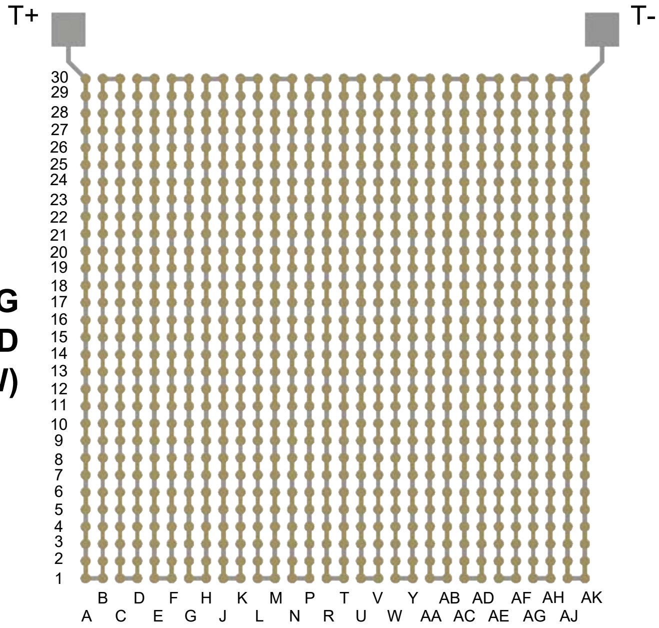
**BOTTOM SIDE
(TOP X-RAY VIEW)**



PC BOARD



**AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)**

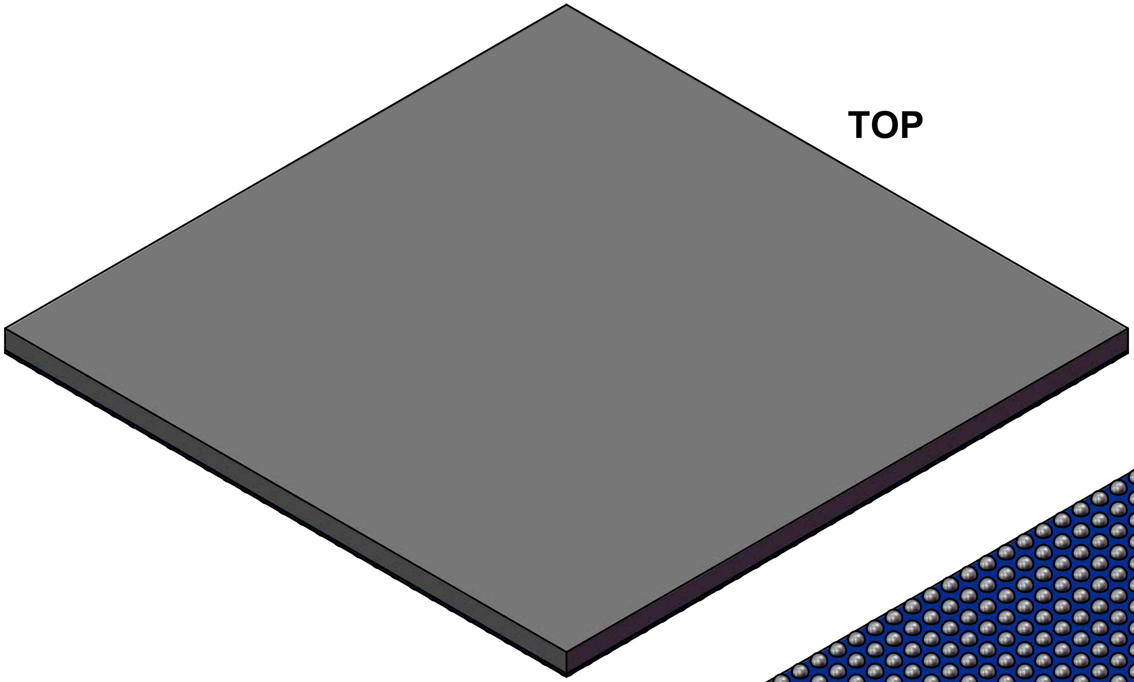


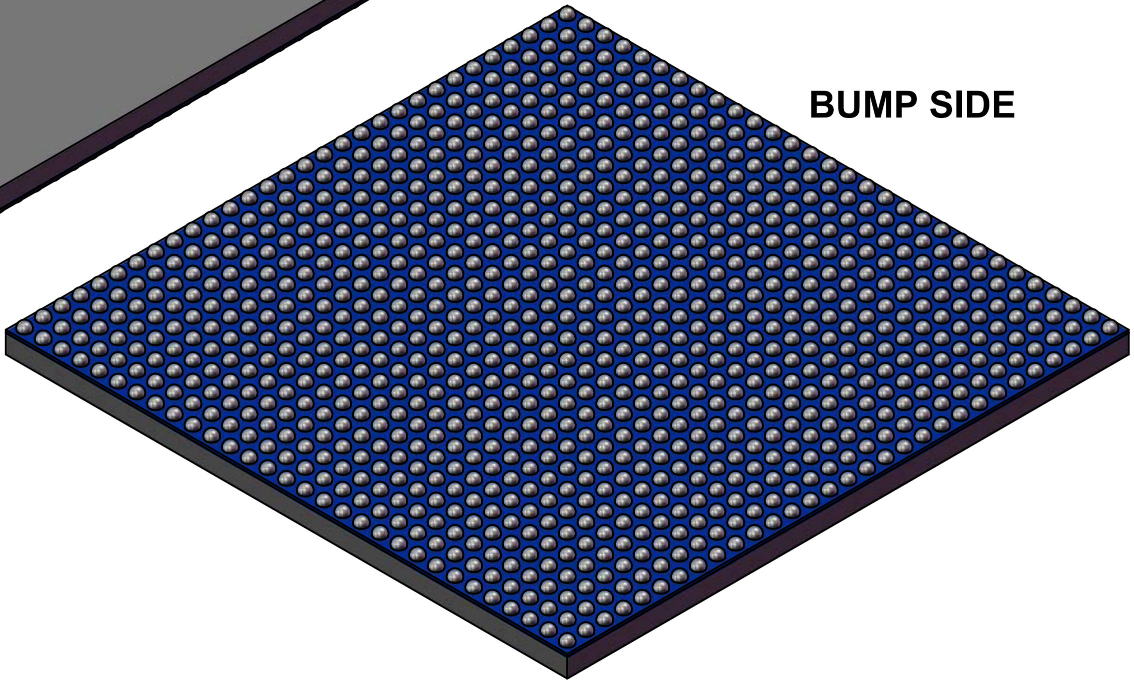
Notes:
1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.
DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
2) PCB Cu BALL PAD DIAMETER: ∅0.21mm (8.2 mil).
3) PCB DAISY CHAIN TRACING LINE WIDTH: 0.10mm (4 mil).

TopLine®

TITLE	WLP900T.35C-DC307D 900 BALL P=0.35mm		
SCALE 25:1	SIZE A	DRAWING NO. 573070	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 5	

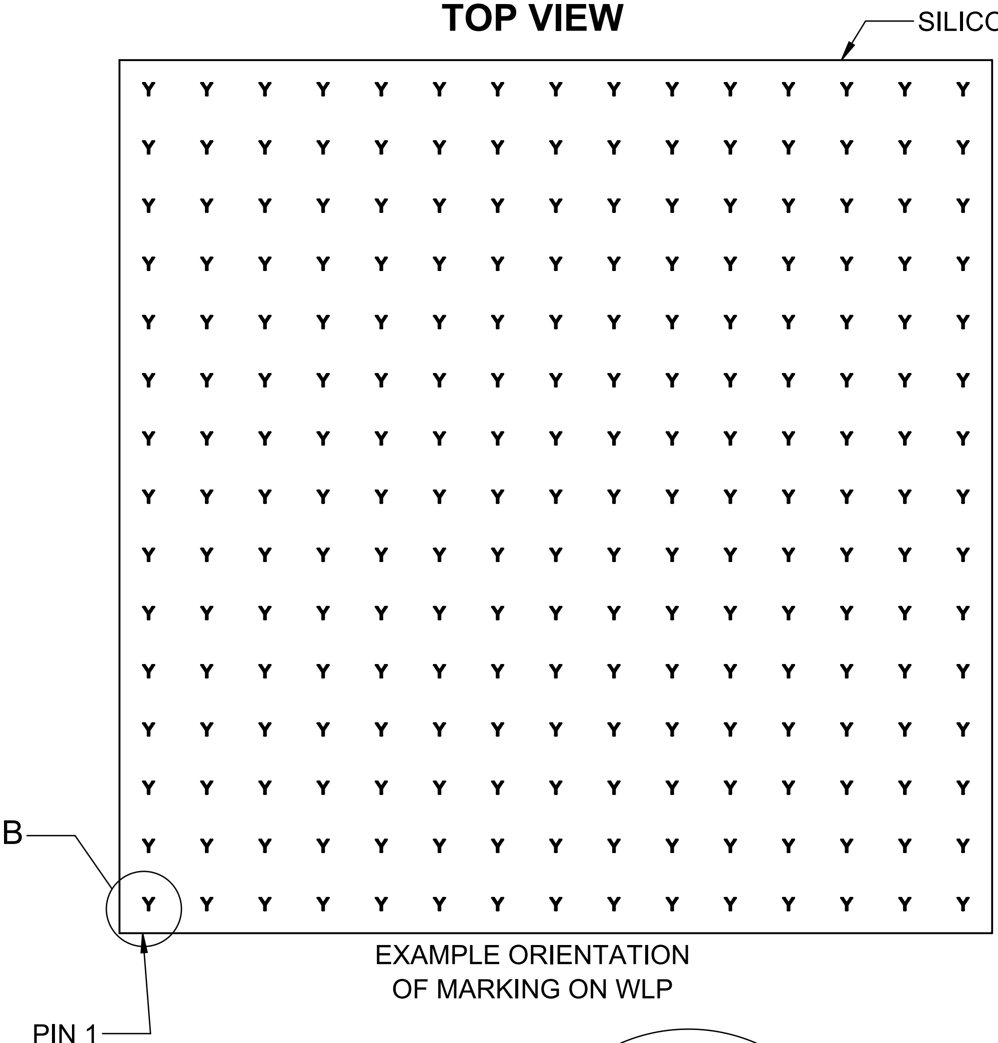
MODEL





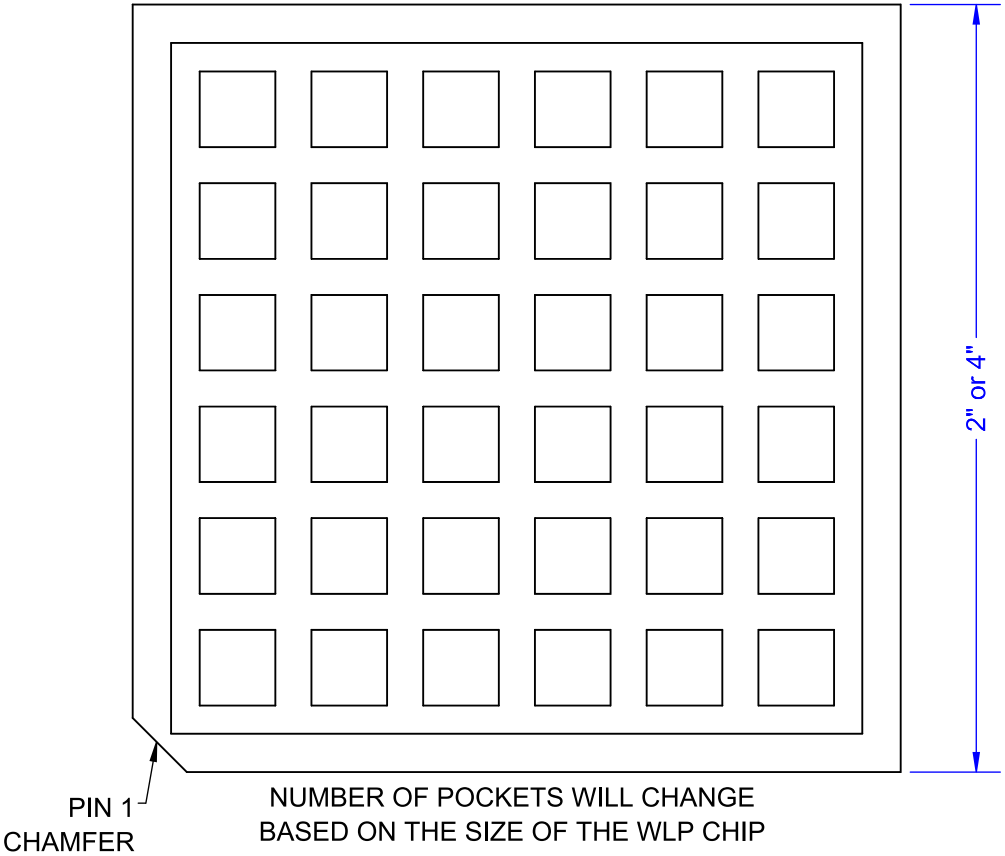
TopLine®			
TITLE	WLP900T.35C-DC307D 900 BALL P=0.35mm		
SCALE 40:1	SIZE A	DRAWING NO. 573070	REV A
DO NOT SCALE DRAWING		SHEET 3 OF 5	

TOP VIEW



EXAMPLE ORIENTATION
OF MARKING ON WLP

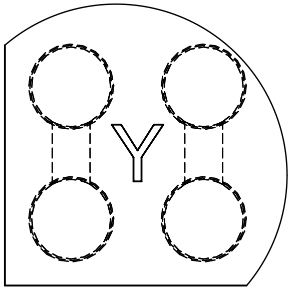
TYPICAL WAFFLE PACK
IC CHIP TRAY SCALE = 2:1



NUMBER OF POCKETS WILL CHANGE
BASED ON THE SIZE OF THE WLP CHIP

Notes: (Unless Otherwise Specified).

1) EXAMPLE OF TOP SIDE LASER MARKING.
2) ORIENT LETTERS FOR LOCATION OF PIN A1 CORNER.
3) ALLOWABLE LETTER MARKING: A, F, T, M, L, Y, AND P.
4) SINGLE LETTER IS REPEATED MULTIPLE TIMES ACROSS TOP SIDE.
5) DAISY CHAIN IS HIDDEN UNDER RESIN ON BALL SIZE.
6) TOP SIDE DOES NOT HAVE A DOT FOR LOCATION OF PIN A1.
7) LETTERS ARE NOT MARKED ON BOTTOM (BALL) SIDE.



DAISY CHAIN
ORIENTATION
DETAIL B
SCALE 50 : 1

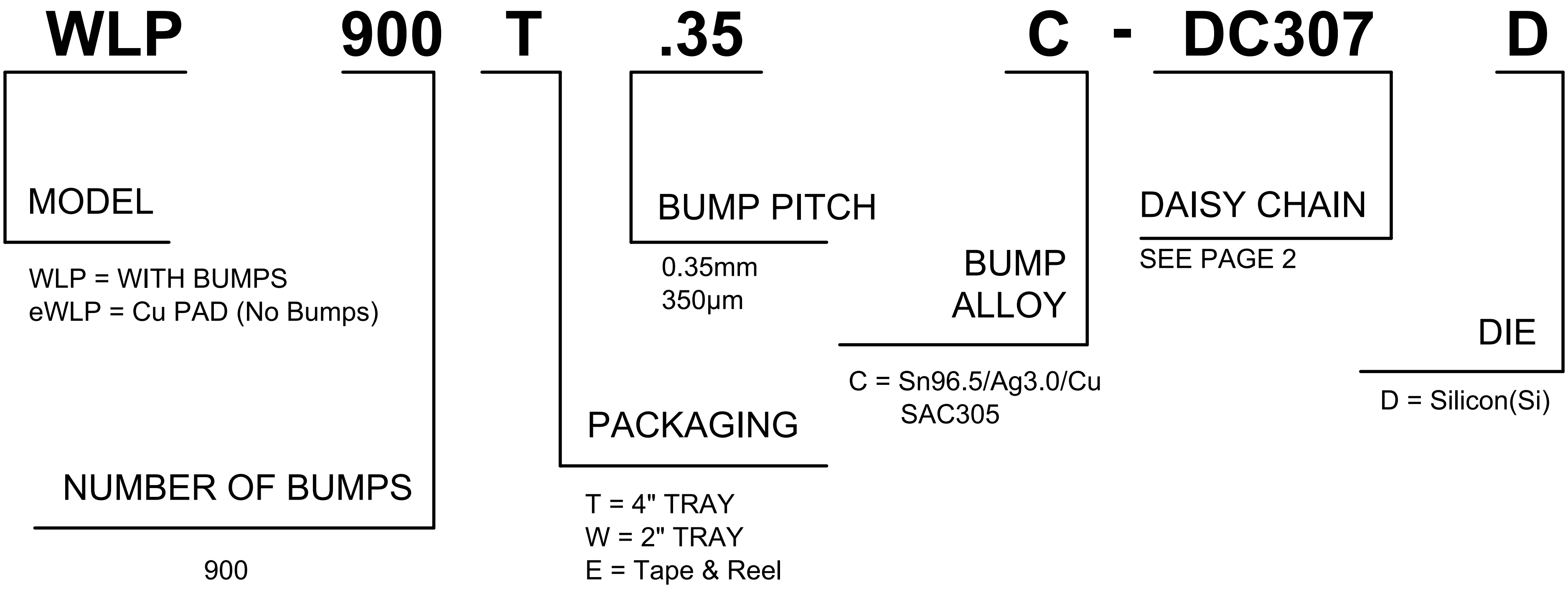
MARKING CODE	
PITCH	**LETTER**
0.35mm	Y

* SUBJECT TO CHANGE

TopLine®

TITLE	WLP900T.35C-DC307D 900 BALL P=0.35mm		
SCALE 30:1	SIZE A	DRAWING NO. 573070	REV A
DO NOT SCALE DRAWING		SHEET 4 OF 5	

PART NUMBER SYSTEM



WLP 900 T .35 C - DC307 D

MODEL

WLP = WITH BUMPS
eWLP = Cu PAD (No Bumps)

NUMBER OF BUMPS

900

PACKAGING

T = 4" TRAY
W = 2" TRAY
E = Tape & Reel

BUMP PITCH

0.35mm
350µm

BUMP ALLOY

C = Sn96.5/Ag3.0/Cu
SAC305

DAISY CHAIN

SEE PAGE 2

DIE

D = Silicon(Si)

PART NUMBER	PACKAING	QTY
WLP900W.35C-DC307D	2" CHIP TRAY	9
WLP900T.35C-DC307D	4" CHIP TRAY	36
WLP900E.35C-DC307D	T&R	500

TopLine®

TITLE	WLP900T.35C-DC307D 900 BALL P=0.35mm		
SCALE 30:1	SIZE A	DRAWING NO. 573070	REV A
DO NOT SCALE DRAWING		SHEET 5 OF 5	